

U.S. Patent Application Serial No. 10/041,609
Amendment dated September 11, 2003
Reply to OA of April 23, 2003

AMENDMENTS TO THE CLAIMS:

This listing of claims will replace all prior versions, and listings, of claims in the application:

Listing of Claims:

1-17 (Canceled)

1
/8. (Currently amended): Semiconductor device having comprising:

a semiconductor substrate having an underlying semiconductor surface;

an insulator film deposited on said underlying semiconductor surface, said insulator film forming a
semiconductor-insulator junction obtained by depositing an insulator film on an underlying semiconductor
surface,

wherein the interfacial level density of said semiconductor-insulator junction is 10^{12} eV⁻¹cm⁻² or less
as a result that, and

said insulator film is deposited on said underlying semiconductor surface after a treatment that
reduces interfacial defects on said semiconductor-insulator junction utilizing a reaction of a treatment gas
supplied ~~with~~ to the semiconductor substrate having said underlying semiconductor surface via a thermal
catalysis body provided near said substrate.

U.S. Patent Application Serial No. **10/041,609**

Amendment dated September 11, 2003

Reply to OA of **April 23, 2003**

¹
~~2~~ ~~19~~. (Previously presented): Semiconductor device as claimed in claim ~~18~~, wherein said semiconductor-insulation junction is one obtained by deposition of said insulator film, which is carried out in said same process chamber after said treatment and utilizes a reaction of a deposition gas supplied with said substrate via said same thermal catalysis body.